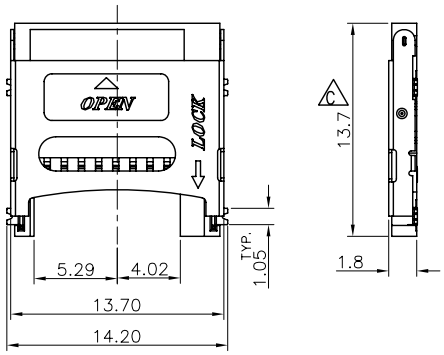
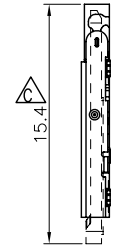
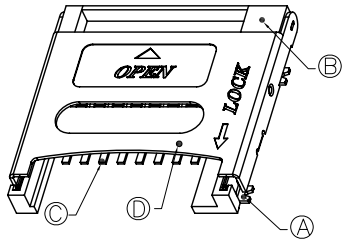
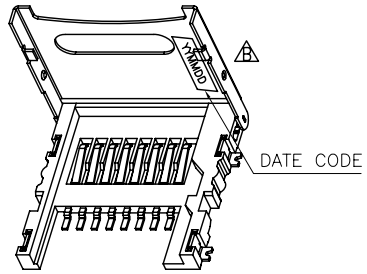
REV.	ECN NO OR DESCRIPTION	REVISED	DATE
A	PRELIMINARY	孫一中	10/08'07
B	⚠B ECR要求修改產品D/C方式 ECN NO.:C070309	孫一中	01/16'08
C	塑膠加膠來增加塑膠強度 ECN NO.:C080051	孫一中	2008.05.02

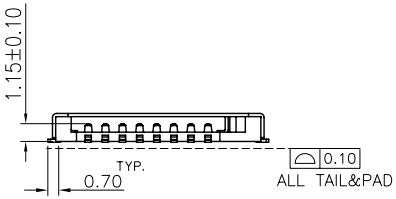


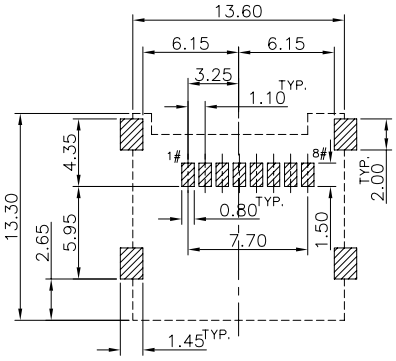


SHELL LOCK

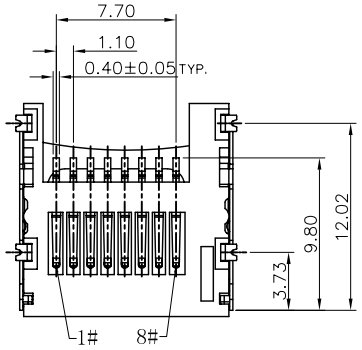








RECOMMENDED PCB PATTERN LAYOUT
TOLERANCE: ±0.05



SPECIFICATIONS:

1. MATERIAL :
   HOUSING:HIGH TEMPERATURE THERMOPLASTIC. UL94V-0.BLACK
   SHELL:STAINLESS STEEL.
   CONTACT:COPPER ALLOY.
   DETECT PIN: COPPER ALLOY.
2. PLATING:
   CONTACT: 1u" Min. Au PLATING IN CONTACT AREA;
   100u"Min.Sn PLEATED OVERALL,
   50u" Min. Ni UNDERPLATED OVERALL.
   PAD:100u" Min. Sn PLATING OVER ALL
   50u"Min. Ni UNDERPLATED OVERALL .
3. ELECTRIACL CHARACTISTIC:
   CONNECT RESISTANCE:80 MILLIONMS/PIN Max.
   INSULATION RESISTANCE:1000 MEGAOHMS Min.
   VOLTAGE WITHSTAND:500V AC for 1minute
4. TO CONFORM TO THE SINGATRON HSF SPEC.
5. DATE CODE: YYMMDD
   Day
   Month
   Year

Pin No.	Name	Type	DESCRIPTION
1	DAT2	I/O/PP	Data Line [bit2]
2	CD/DAT3	I/O/PP	Card Detect Data Line [bit3]
3	CMD	PP	Command Response
4	VDD	S	Supply Voltage
5	CLK	I	Clock
6	VSS	S	Supply Voltage Ground
7	DAT0	I/O/PP	Data Line [bit0]
8	DAT1	I/O/PP	Data Line [bit1]

NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR
D	Shell	1	STAINLESS STEEL.	/
C	Contact	8	COPPER ALLOY	SEE TABLE
B	Housing	1	HIGH TEMP. THERMOPLASTIC	(UL94-V0).BLACK
A	Sold Pin	4	COPPER ALLOY	Sn:100u"min Ni:50u"min

UNLESS OTHERWISE SPECIFED TOLERANCES

DECIMALS: ANGLES:
X :±0.5 X :±2°
X.X :±0.3 X.X :±1°
X.XX :±0.2

Singatron Enterprise Co., Ltd.
信音企業股份有限公司

TITLE	TRANS FLASH HIGNE			
DWN	孫一中	PART NO. 2CA2000-000111		
CHKD		SCALE 3:1	UNIT: mm	
APVD	MUYUAN	SIZE: A3	SHEET: 1OF1	REV: C

CUSTOMER COPY

文件編號 RD-06-043-A